Board Stack Report Stack Up Layer Stack **Board Layer Stack** Material Thickness Constant Name Layer Top Paste 2 Top Overlay 3 Top Solder Solder Resist 0.40mil 3.5 1.38mil 4 Top Layer Copper 5 Dielectric 1 PP-017 5.10mil 4.3 6 1.38mil Layer 1 Copper Dielectric 2 Core-025 8.00mil 4.6 8 Layer 2 Copper 1.38mil 9 Dielectric 3.1 PP-017 5.10mil 4.3 10 Dielectric 3.2 PP-017 5.10mil 4.3 11 Layer 3 Copper 1.38mil 12 Dielectric 4 Core-025 8.00mil 4.6 13 Layer 4 Copper 1.38mil Dielectric 5.1 14 PP-017 5.10mil 4.3 15 Dielectric 5.2 PP-017 5.10mil 4.3 16 Layer 5 1.38mil Copper 17 Dielectric 6 Core-025 8.00mil 4.6 18 Layer 6 Copper 1.38mil 19 Dielectric 7 PP-017 4.3 5.10mil 1.38mil 20 **Bottom Layer** Copper 21 **Bottom Solder** Solder Resist 0.40mil 3.5 22 **Bottom Overlay** 23 **Bottom Paste** Height: 66.42mil